Title (en)

Resin sealing type semiconductor device

Title (de)

Harzvergossenes Halbleiterbauteil

Title (fr)

Dispositif semi-conducteur du type à encapsulation par résine

Publication

EP 0854511 B1 20090708 (EN)

Application

EP 98100152 A 19980107

Priority

- JP 751997 A 19970120
- JP 27439297 A 19971007

Abstract (en)

[origin: EP0854511A2] A resin sealing type semiconductor device capable of making a resin burr hard to occur when formed by molds and of restraining cracks in solder, is actualized by providing a stepped portion on a resin sealing body for covering a circuit forming surface of a semiconductor chip, making leads exposed from this exposed surface and joining solder bumps to the leads. <IMAGE>

IPC 8 full level

H01L 23/28 (2006.01); **H01L 23/31** (2006.01); **H01L 23/12** (2006.01); **H01L 23/495** (2006.01); **H01L 23/50** (2006.01); H05K 3/30 (2006.01); H05K 3/34 (2006.01)

CPC (source: EP KR US)

H01L 23/28 (2013.01 - KR); **H01L 23/3114** (2013.01 - EP US); **H01L 23/4951** (2013.01 - EP US); H01L 24/45 (2013.01 - EP US); H01L 24/48 (2013.01 - EP US); H01L 2224/32245 (2013.01 - EP US); H01L 2224/45144 (2013.01 - EP US); H01L 2224/48091 (2013.01 - EP US); H01L 2224/48247 (2013.01 - EP US); H01L 2224/4826 (2013.01 - EP US); H01L 2224/48465 (2013.01 - EP US); H01L 2224/73215 (2013.01 - EP US); H01L 2924/00014 (2013.01 - EP US); H01L 2924/01078 (2013.01 - EP US); H01L 2924/01079 (2013.01 - EP US); H01L 2924/07802 (2013.01 - EP US); H01L 2924/14 (2013.01 - EP US); H01L 2924/15311 (2013.01 - EP US); H01L 2924/1815 (2013.01 - EP US); H05K 3/303 (2013.01 - EP US); H05K 3/3442 (2013.01 - EP US)

Cited by

US7307347B2; EP1189279A4; US7704801B2

Designated contracting state (EPC)

DE FR GB NL

DOCDB simple family (publication)

EP 0854511 A2 19980722; **EP 0854511 A3 20000426**; **EP 0854511 B1 20090708**; DE 69840953 D1 20090820; JP 3793628 B2 20060705; JP H10261753 A 19980929; KR 100480543 B1 20050616; KR 19980070254 A 19981026; TW 388974 B 20000501; US 5999413 A 19991207

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EP 98100152 A 19980107; DE 69840953 T 19980107; JP 27439297 A 19971007; KR 19970076812 A 19971229; TW 86119303 A 19971219; US 99079097 A 19971215